

# Release Film ACC-8

Version: A1

## Lamination-Accessories

### Product Description

Release film plays an integral role in the lamination of Printed Circuit Boards. ACC-8 Release film was developed to address the needs of this demanding process and provide the user with a functionally superior product that is environmentally safe.

Below are the major features and benefits of ACC-8 Release Film. These advantages clearly make ACC-8 "The Ultimate Release Film".

- > **Excellent release properties**  
Can be used against copper, stainless steel, aluminium, prepreg both cured & "B" staged and oxidized copper surfaces. Releases easily and cleanly from the above materials.
- > **Static-free**  
Dirt and dust will not adhere to film surface. Assures clean and uniform lamination without static cling.
- > **Odourless**  
No offensive or hazardous gases emitted, potentially endangering health of employees.
- > **Dimensionally stable**  
Does not shrink, assuring stable multilayer and laminate package. Reduces wrinkling of copper foil.
- > **Remains flexible**  
Will not embrittle, even at temperatures above 175 °C. Assures consistent and uniform heat transfer and release.
- > **Smear and scum free**  
Eliminates contamination of plates, reducing unnecessary down-time for cleaning.

- > **Environmentally safe**  
Can be incinerated or disposed in landfill. No hazardous gases emitted.

### Availability

The standard size is in rolls 0,66 m wide and 1000 m long (660 m<sup>2</sup>).

Upon special request intermediate dimensions can be supplied, also sheets.

Technical Data	
Nominal Thickness:	30 µm ± 0,003 mm
Colour:	Translucent, clear
Max. Operating Temperature:	≤190 °C
Melting Point:	250-260 °C
Tensile Strength:	150 N/mm <sup>2</sup>
Elongation:	100 %

### General Safety Information

- > Only use the product for applications described in the product data sheet
- > The product is intended for industrial use only
- > The product is not suitable for food industry
- > The product must not be eaten

Disclaimer: The information and data contained in this technical literature is based on data and knowledge correct at the time of publishing/printing and is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.